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First Named Inventor	Yi Li
Title	Process Techniques for Preparing Moisture Management Textiles
Attorney Docket Number	LUNGHK/107/US
Date	May 13, 2005

Mail Stop Assignment Recordation Services Director of the United States Patent and Trademark Office, P.O. Box 1450, Alexandria, Virginia 22313-1450

Please record the attached document.

1. Name of conveying party(ies):

Yi Li Qing Wen Song Jun Yan Hu

2. Name and address of receiving party(ies):

Name: The Hong Kong Polytechnic University
Street Address: Hunghom
City, State, ZIP: Kowloon, Hong Kong
Country: China

Country of Incorporation: Hong Kong educational institution

3. Nature of Conveyance: Assignment
Execution Date: April 25, 2005

4. Application No. 11/050,509 filed February 3, 2005

5. Name and address of party to whom correspondence document should be mailed:

Guy D. Yale, Esq.
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6. Total number of applications involved: 1
7. Total fee enclosed: \$40.00. If this amount is incorrect, please charge or credit the difference to Deposit Account No. 16-2563.
8. Total number of pages including cover sheet, attachments and documents: 3

To the best of my knowledge and belief, the foregoing information is true and correct.

SIGNATURE OF APPLICANT, ATTORNEY OR AGENT

Firm or Individual name	Guy D. Yale	Reg. No.	29,125
Signature			
Date	May 13, 2005	Attorney's Docket No.	LUNGHK/107/US

OPR/FINANCE
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ASSIGNMENT

WHEREAS, we, Yi Li, Qing Wen Song and Jun Yan Hu, each residing at Institute of Textiles and Clothing, The Hong Kong Polytechnic University Hunghom, Kowloon, Hong Kong, China, have invented new and useful improvements in

**Processing Techniques for Preparing Moisture
Management Textiles**

for which we have made application for Letters Patent of the United States, which application was filed on February 3, 2005 under Serial No. 11/050,509 and

WHEREAS, The Hong Kong Polytechnic University, a Hong Kong educational institution, having an address at Hunghom, Kowloon, Hong Kong, China, is desirous of acquiring the entire right, title and interest in and to said improvements and any Letters Patent which may be granted thereon;

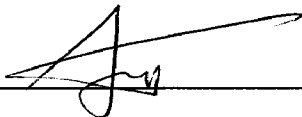
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for and in consideration of the sum of One (1) Dollar to us in hand paid and other good and valuable consideration, receipt of which is hereby acknowledged, we, the said Yi Li, Qing Wen Song and Jun Yan Hu, sell, assign and transfer to The Hong Kong Polytechnic University, its successors and assigns (hereinafter called "Assignee"), the entire right, title and interest in and to said improvements and in and to any Letters Patent which may be obtained thereon in the United States and in all countries foreign thereto, together with said application and all divisional, continuing, substitute, renewal, reissue, and other applications for Letters Patent which have been or may be filed on said improvements in the United States or any other country; the same to be held and enjoyed by the Assignee for its and their sole use and behoof; and we do hereby further assign to the Assignee the right to file applications for patent in all countries on said improvements and all rights of priority resulting from any application for Letters Patent filed on said improvements.

We hereby authorize and request the Commissioner of Patents and Trademarks to issue all Letters Patent of the United States on said improvements to the Assignee.

We further covenant and agree that when requested by the Assignee, and without further consideration, but at the cost and expense of the Assignee, we will, for any and all countries, execute and deliver all applications for patent on said improvements, execute all lawful oaths and other papers, supply to the Assignee all facts and evidence known to us relating to said improvements and the history and development thereof, testify in all interferences, suits, and other legal proceedings, and generally do everything rightful which the Assignee shall consider desirable for aiding in securing, maintaining, and enforcing proper patent protection for said improvements and for vesting the title to said improvements in the Assignee.

We further covenant that we have the lawful right to assign the interest in said improvements in the manner and form as herein expressed and that the interests herein conveyed are free from prior assignment, grant, mortgage, license, or other encumbrance whatsoever and that the execution of this Assignment is our own free act and deed.


Date: 25 - April - 05


Yi Li

Lv Ru
Witness

王树晓
Witness


Date: 25 - April - 05


Qing Wen Song

Lv Ru
Witness

王树晓
Witness

Date: 25 - April - 05


Jun Yan Hu

Lv Ru
Witness

王树晓
Witness